

### Features

- Frequency range : 24MHz to 80MHz
- Extremely small SMD type crystal
- 4 pad AuSn sealing, ceramic package
- High precision and frequency stability
- External dimensions (mm)  
L : 1.2 x W : 1.0 x H : 0.33
- RoHS and REACH compliant & Pb free

### Applications

- Wearable devices
- Wi-Fi, BT or other wireless module
- IoT devices
- Smart phone
- Space limited application

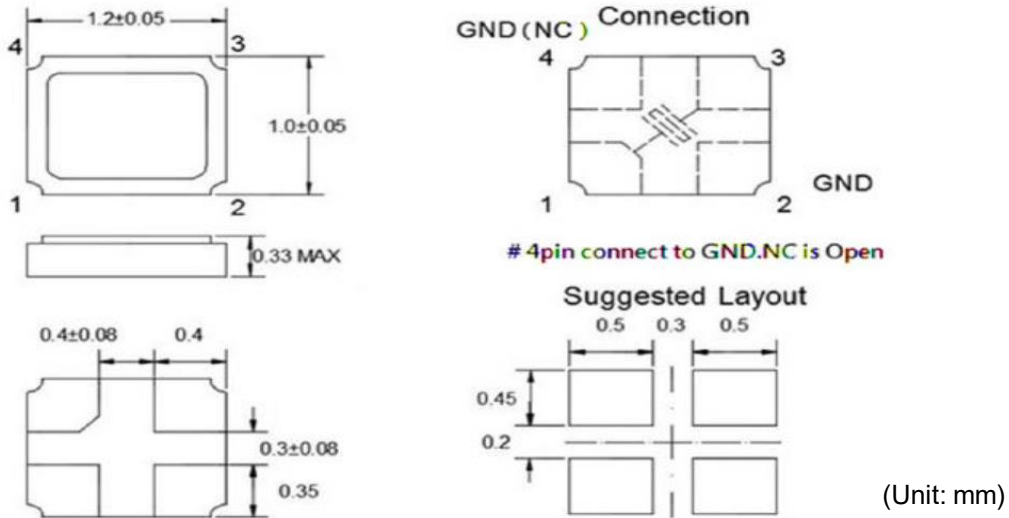
### Electrical Characteristics

Item		8J	Conditions
Frequency Range	$F_0$	24MHz ~ 80MHz	
Frequency Tolerance	$F_{tol}$	±30ppm, ±20ppm, ±10ppm	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	$F_{stab}$	±30 ppm	-20°C ~ +70°C
		±20 ppm	
		±10 ppm	
		±10 ppm	-30°C ~ +85°C
		±30 ppm ±20 ppm	-40°C ~ +85°C
Operating Temperature Range	$T_{OTR}$	-20°C ~ +70°C	
		-40°C ~ +85°C	
Shunt Capacitance	$C_0$	3pF Max.	
Drive Level	$D_L$	1 ~ 200μW (100μW Typ.)	
Load Capacitance	$C_L$	6pF, 8pF, 10pF, 12pF	
Aging	$F_{aging}$	±3 ppm Max.	at 25°C ± 3°C, first year
Storage Temperature Range	$T_{STR}$	-55°C ~ +125°C	

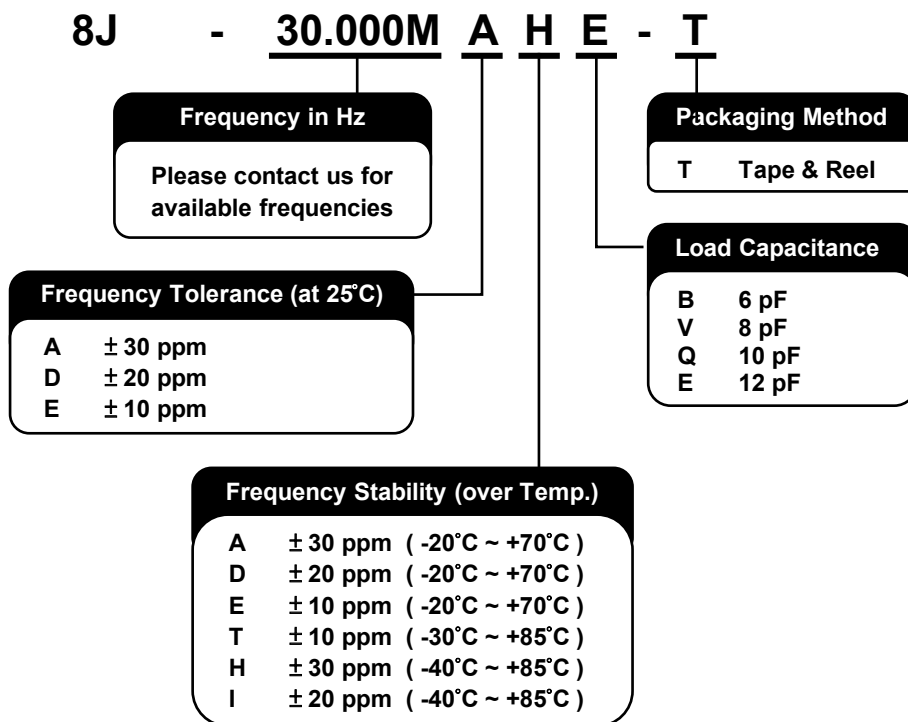
### Motional Resistance (ESR)

Fundamental	
24 ~ 32 MHz	100Ω Max.
37.4 ~ 48 MHz	80Ω Max.
> 48 MHz	60Ω Max.

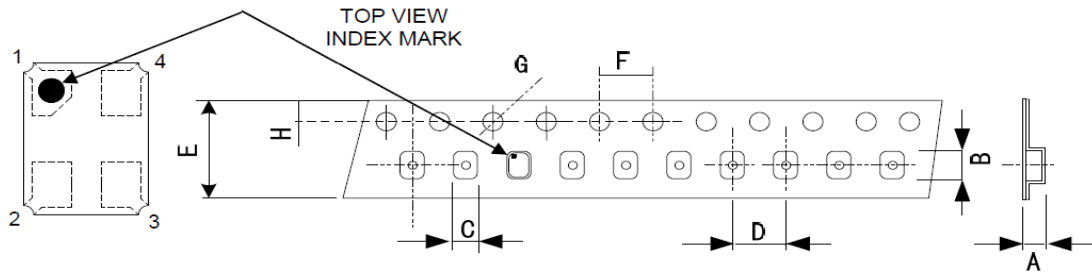
### Dimensions



### Ordering Information

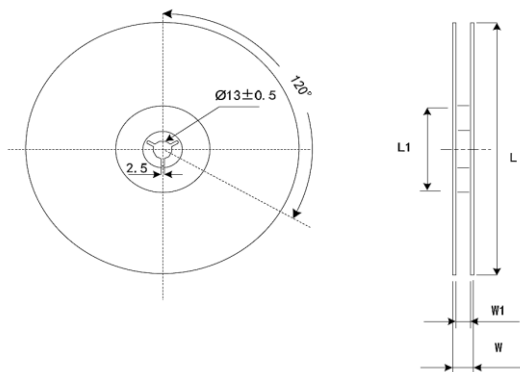


### Packing



DIMENSIONS	A	B	C	D	E	F	G	H
	0.45	1.30	1.10	4.00	8.00	4.00	1.55	1.75
	±0.05	±0.05	±0.05	±0.10	±0.20	±0.10	±0.05	±0.10

(Unit: mm)



DIMENSIONS	L	L1	W	W1
	178	60.2	11.5	8
	±1.00	±0.50	±0.2	+1/-0

(Unit: mm)

### Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

